

Claim 5 (original): A method of making an Al-Cu bonded structure according to claim 4 wherein, when said insert material has a thickness of 100 microns, said brazing is performed at a temperature of 823 K +/- 5K (550 deg C +/- 5 deg C) with a brazing time of no more than 1800 sec, and a layer of said Ag is made to remain between the Al-Cu components.

Claim 6 (original): A method of making an Al-Cu bonded structure according to claim 3 or claim 4 wherein said remaining Ag layer has a thickness of 10 μm or more.

Claim 7 (currently amended): A thin Al-Cu bonded structure comprising:

an Al component;

a Cu component; and

Ag as an insert material in the interlayer between the Al component and the Cu component, which includes a mesh of Ag_2Al intermetallic component,

wherein the resultant Al-Cu brazed bonded component is rolled to produce the Al-Cu bonded structure.

Claim 8 (original): A thin Al-Cu bonded structure as described in claim 7 wherein hot rolling is performed on said Al-Cu brazed bonded component.

Claim 9 (original): A thin Al-Cu bonded structure as described in claim 7 or claim 8 wherein said structure has a thickness of 0.1 mm or more.

Claim 10 (original): A method of making a thin Al-Cu bonded structure comprising: providing a brazed bonded component comprising an Al component, a Cu component, and Ag as an insert material in the interlayer between the Al component and the Cu component; and rolling the brazed bonded component.

Claim 11 (original): A method for making a thin Al-Cu bonded structure according to claim 10 wherein said rolling is performed as hot rolling.

